



THE DATASHEET OF MR2535LRL



MR2535L

Overvoltage Transient Suppressors

Medium Current

Designed for applications requiring a low voltage rectifier with reverse avalanche characteristics for use as reverse power transient suppressors. Developed to suppress transients in the automotive system, these devices operate in the forward mode as standard rectifiers or reverse mode as power avalanche rectifier and will protect electronic equipment from overvoltage conditions.

Features

- Avalanche Voltage 24 to 32 V
- High Power Capability
- Economical
- Increased Capacity by Parallel Operation
- Pb-Free Packages are Available*

Mechanical Characteristics:

- Case: Epoxy, Molded
- Weight: 2.5 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Maximum Lead Temperature for Soldering Purposes: 350°C 3/8" from Case for 10 Seconds at 5 lbs. Tension
- Polarity: Indicated by Diode Symbol or Cathode Band

MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Rating	Symbol	Value	Unit
DC Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	20	V
Repetitive Peak Reverse Surge Current (Time Constant = 10 ms, Duty Cycle \leq 1%, $T_C = 25^\circ\text{C}$)	I_{RSM}	62	A
Average Rectified Forward Current (Single Phase, Resistive Load, 60 Hz, $T_C = 125^\circ\text{C}$) (Figure 4)	I_O	6.0	A
Non-Repetitive Peak Surge Current Surge Supplied at Rated Load Conditions Halfwave, Single Phase	I_{FSM}	600	A
Operating and Storage Junction Temperature Range	T_J, T_{stg}	-65 to +175	$^\circ\text{C}$

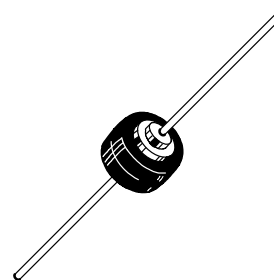
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



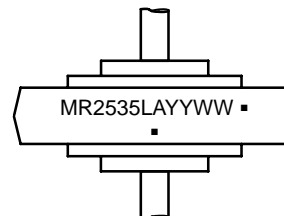
ON Semiconductor®

<http://onsemi.com>



MICRODE AXIAL
CASE 194
STYLE 1

MARKING DIAGRAM



A = Assembly Location
YY = Year
WW = Work Week
▪ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
MR2535L	Microde Axial	1000 Units/Box
MR2535LG	Microde Axial (Pb-Free)	1000 Units/Box
MR2535LRL	Microde Axial	800/Tape & Reel
MR2535LRLG	Microde Axial (Pb-Free)	800/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MR2535L

THERMAL CHARACTERISTICS

Characteristic	Lead Length	Symbol	Max	Unit
Thermal Resistance, Junction-to-Lead @ Both Leads to Heatsink, Equal Length	1/4" 3/8" 1/2"	$R_{\theta JL}$	7.5 10 13	$^{\circ}\text{C}/\text{W}$
Thermal Resistance Junction-to-Case		$R_{\theta JC}$	0.8 (Note 1)	$^{\circ}\text{C}/\text{W}$

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
Instantaneous Forward Voltage (Note 2) ($I_F = 100\text{ A}$, $T_C = 25^{\circ}\text{C}$)	V_F	-	1.1	V
Reverse Current ($V_R = 20\text{ Vdc}$, $T_C = 25^{\circ}\text{C}$)	I_R	-	200	nAdc
Breakdown Voltage (Note 2) ($I_R = 100\text{ mAdc}$, $T_C = 25^{\circ}\text{C}$)	$V_{(BR)}$	24	32	V
Breakdown Voltage (Note 2) ($I_R = 90\text{ A}$, $T_C = 150^{\circ}\text{C}$, $PW = 80\text{ }\mu\text{s}$)	$V_{(BR)}$	-	40	V
Breakdown Voltage Temperature Coefficient	$V_{(BR)TC}$	-	0.096 (Note 1)	$\%/^{\circ}\text{C}$
Forward Voltage Temperature Coefficient @ $I_F = 10\text{ mA}$	V_{FTC}	-	2 (Note 1)	$\text{mV}/^{\circ}\text{C}$

- Typical.
- Pulse Test: Pulse Width $\leq 300\text{ }\mu\text{s}$, Duty Cycle $\leq 2\%$.

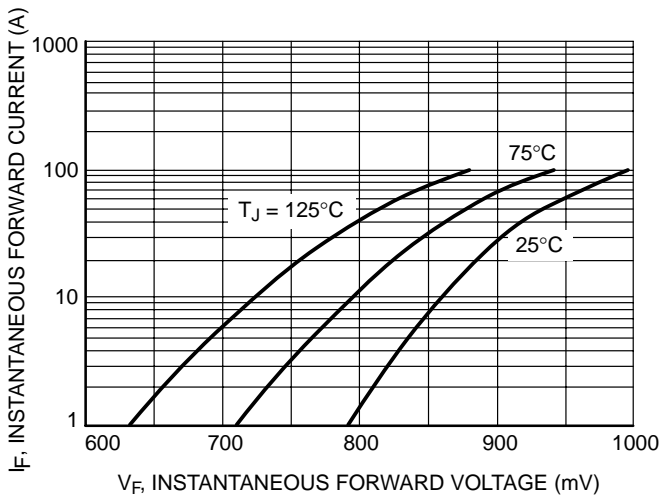


Figure 1. Typical Forward Voltage

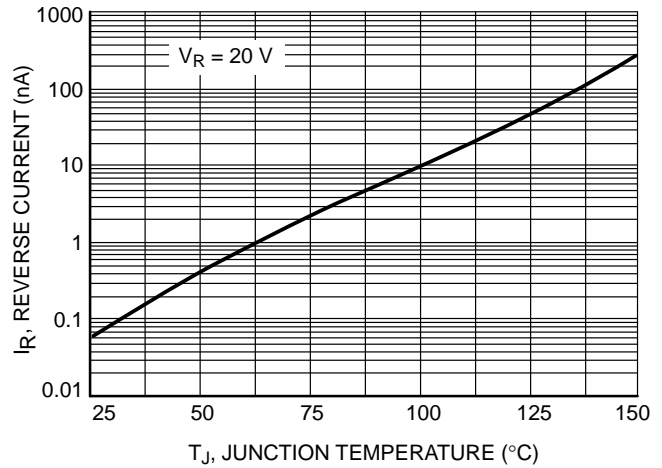


Figure 2. Typical Reverse Current versus Junction Temperature

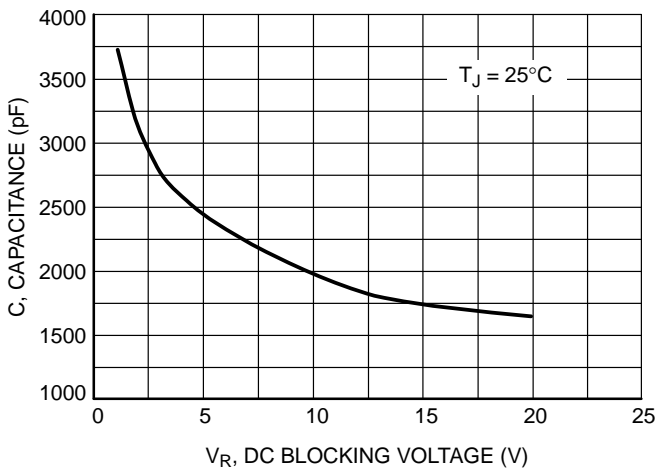


Figure 3. Typical Capacitance

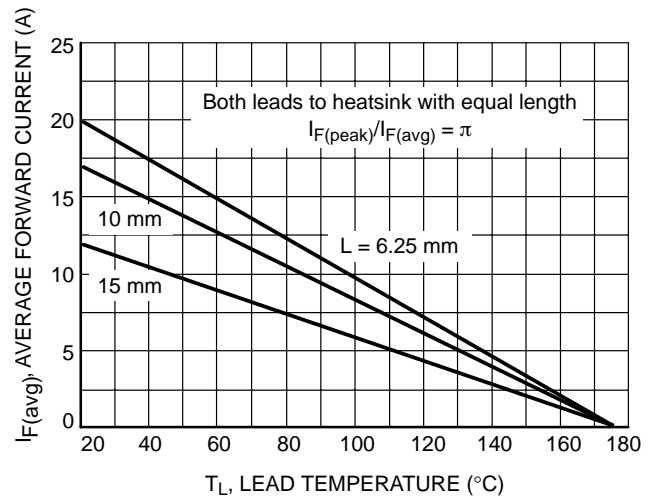


Figure 4. Maximum Current Ratings

MR2535L

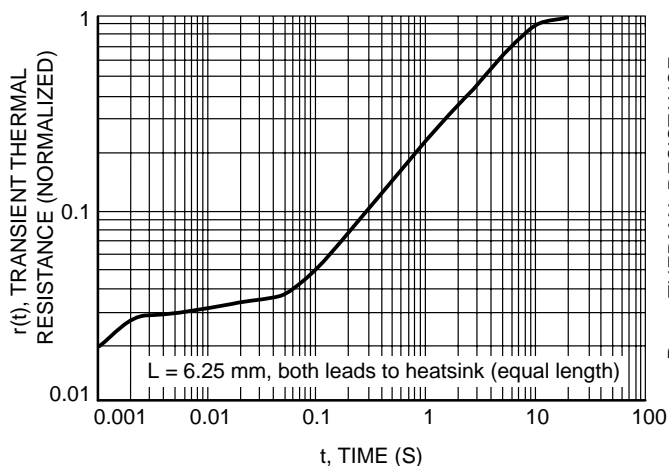


Figure 5. Thermal Response

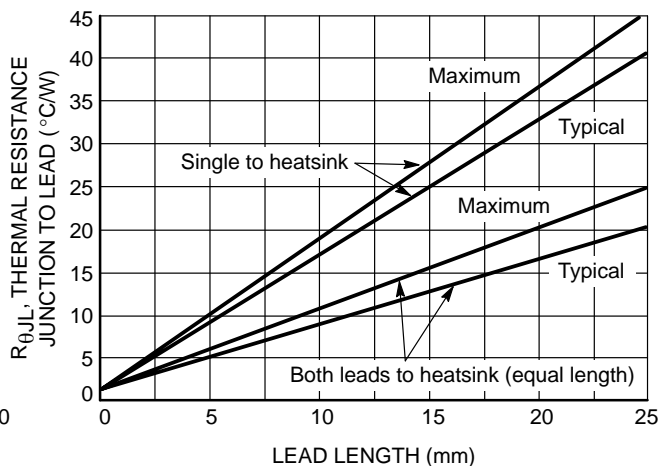


Figure 6. Steady State Thermal Resistance

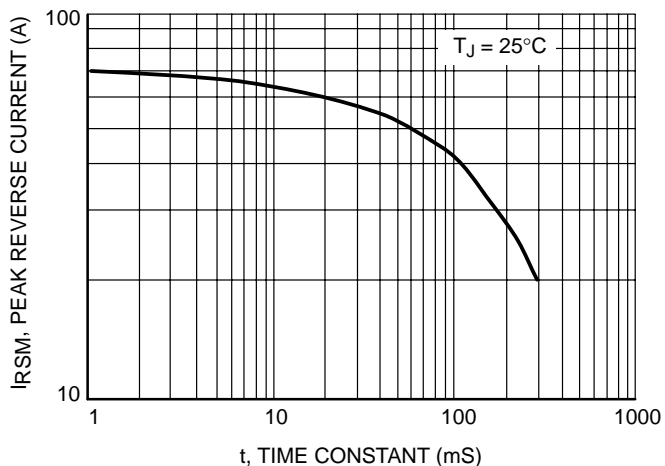


Figure 7. Maximum Peak Reverse Current

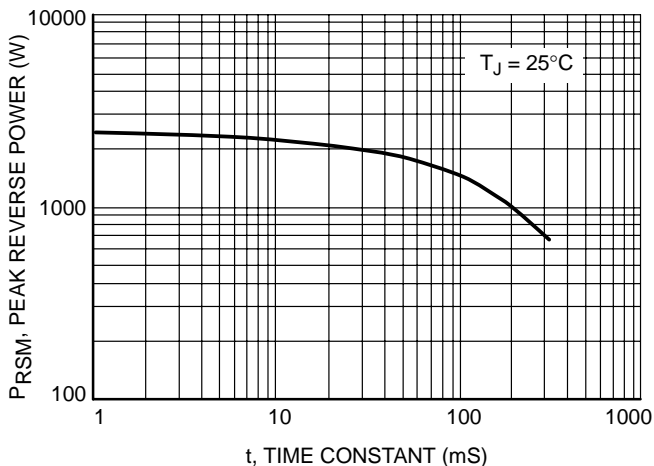


Figure 8. Maximum Peak Reverse Power

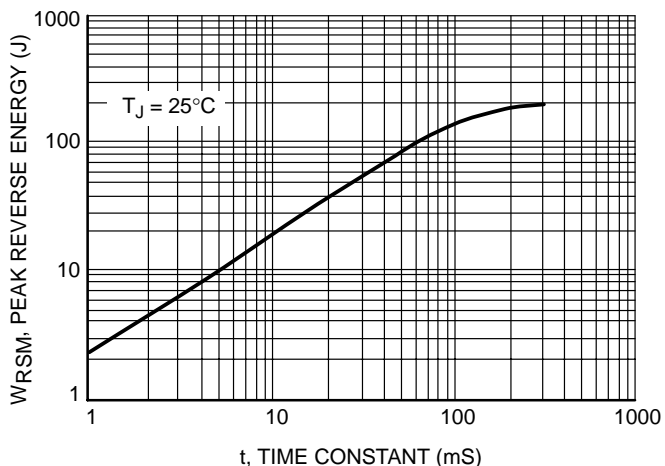


Figure 9. Maximum Reverse Energy

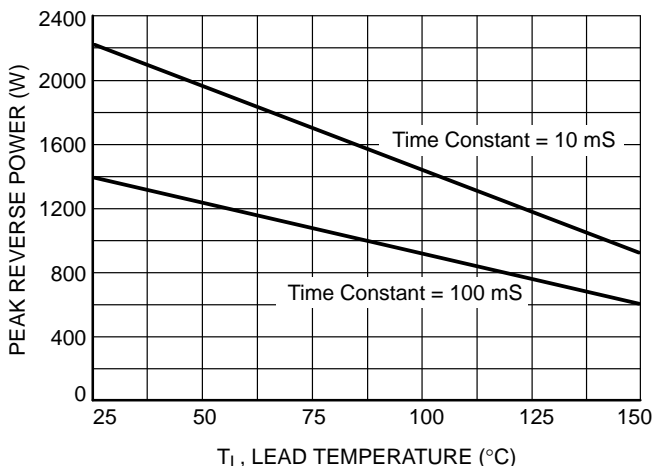


Figure 10. Reverse Power Derating

MR2535L

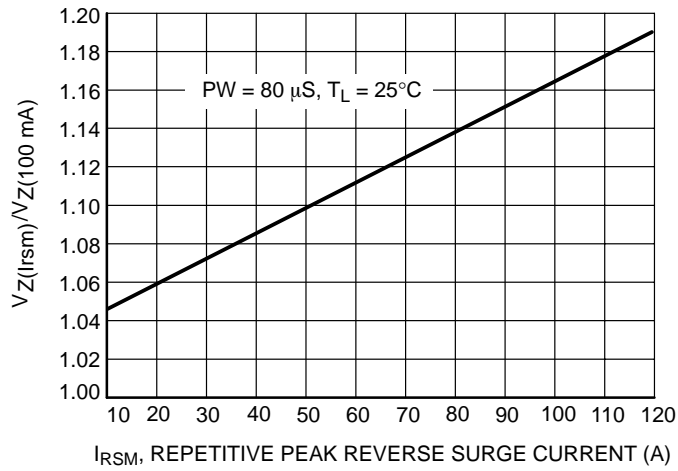


Figure 11. Typical Clamping Factor

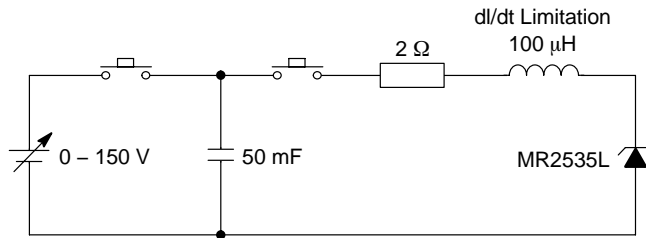


Figure 12. Load Dump Test Circuit

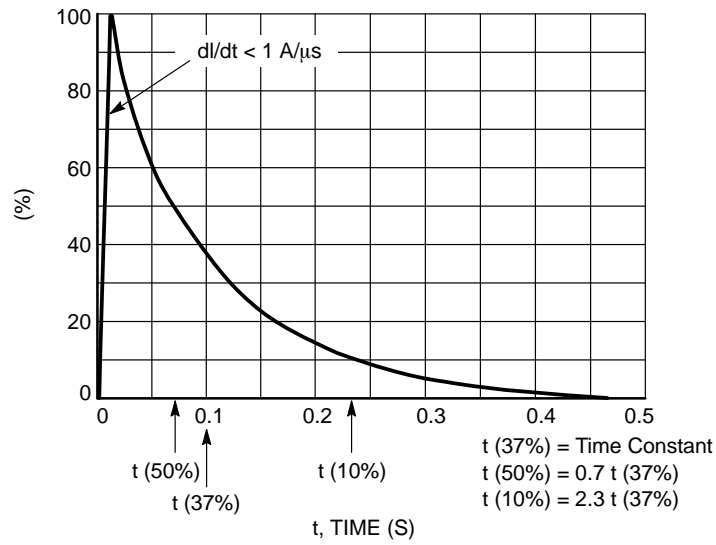
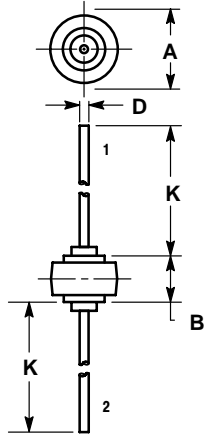


Figure 13. Load Dump Pulse Current

MR2535L

PACKAGE DIMENSIONS


MICRODE AXIAL CASE 194-04 ISSUE H



- NOTES:
1. CATHODE SYMBOL ON PACKAGE.
2. 194-01 OBSOLETE, 194-04 NEW STANDARD.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	8.43	8.69	0.332	0.342
B	5.94	6.25	0.234	0.246
D	1.27	1.35	0.050	0.053
K	25.15	25.65	0.990	1.010

- STYLE 1:
PIN 1. CATHODE
2. ANODE

ON Semiconductor and  are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada
Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free
USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81-3-5773-3850

ON Semiconductor Website: www.onsemi.com
Order Literature: <http://www.onsemi.com/orderlit>
For additional information, please contact your local
Sales Representative

Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

- ⊖ [View MR2535LRL on WIN SOURCE](#)
- ⊖ [ON Semiconductor Information](#)

Optimize Your Supply Chain with WIN SOURCE Solutions

- ✓ Global Sourcing Solution
- ✓ Obsolete Management
- ✓ Cost Control Management
- ✓ Shortage Management
- ✓ Alternative Solution
- ✓ Excess Inventory Management